

Electronic Acknowledgement Receipt

EFS ID:	9025687
Application Number:	10755042
International Application Number:	
Confirmation Number:	8665
Title of Invention:	Integrated chip package structure using silicon substrate and method of manufacturing the same
First Named Inventor/Applicant Name:	Mou-Shiung Lin
Customer Number:	89518
Filer:	Dennis Alan Duchene/ShirLynn Mata
Filer Authorized By:	Dennis Alan Duchene
Attorney Docket Number:	085027-0104
Receipt Date:	13-DEC-2010
Filing Date:	09-JAN-2004
Time Stamp:	20:05:22
Application Type:	Utility under 35 USC 111(a)

Payment information:

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Payment Type	Deposit Account
Payment was successfully received in RAM	\$ 180
RAM confirmation Number	6878
Deposit Account	502624
Authorized User	
The Director of the USPTO is hereby authorized to charge indicated fees and credit any overpayment as follows: Charge any Additional Fees required under 37 C.F.R. Section 1.21 (Miscellaneous fees and charges)	

File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1	Transmittal Letter	InformationDisclosureState mentTransmittal1-085027-0104.pdf	71355 ee0128ab30226c3413d53f9d0f8c3354866a2a7	no	3
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2	Information Disclosure Statement (IDS) Filed (SB/08)	InformationDisclosureState ment1-085027-0104.pdf	88479 905da92d0f173ae0942e154215e05eb211c10028d8	no	1
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35	NPL Documents	26_PDF_MEGICA_Brochure_Leaflets_01_28_04_pdf_pdf.pdf	888383 <small>acc08485e67eb17d813ea762144d8b5c181f889a</small>	no	3
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Total Files Size (in bytes):			46820436		
<p>This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.</p> <p><u>New Applications Under 35 U.S.C. 111</u></p> <p>If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.</p> <p><u>National Stage of an International Application under 35 U.S.C. 371</u></p> <p>If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.</p> <p><u>New International Application Filed with the USPTO as a Receiving Office</u></p> <p>If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.</p>					